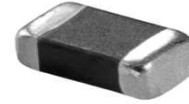


# Chip Bead For GHz noise suppression

## CIV05 Series (1005/ EIA 0402)

### APPLICATION

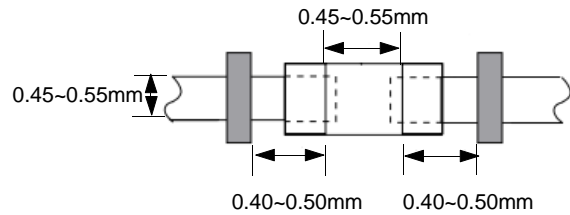
High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.



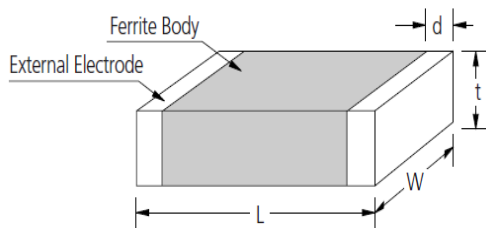
### FEATURES

- CIV Series have high impedance in a GHz band and suppress GHz noise which is usually made due to high frequency of the electronic appliances, high speed and mass storage of the data.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability

### RECOMMENDED LAND PATTERN



### DIMENSION



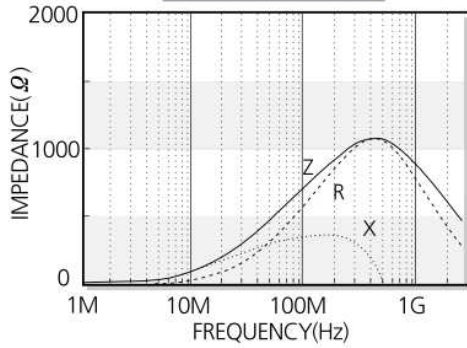
Type	Dimension [mm]			
	L	W	t	d
05	1.0±0.05	0.5±0.05	0.5±0.05	0.25±0.1

### DESCRIPTION

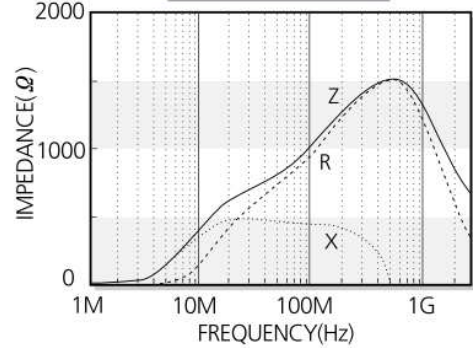
Part no.	Impedance (Ω)±25%@100MHz	Impedance (Ω)±40%@1GHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIV05U601	600	1000	0.7	300
CIV05U102	1000	1400	1.1	250
CIV05J102	1000	2000	1.25	250
CIV05J182	1800	2700	2.20	200

**CHARACTERISTIC DATA**

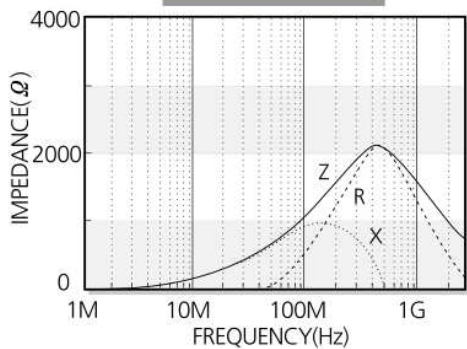
**CIV05U601NC**



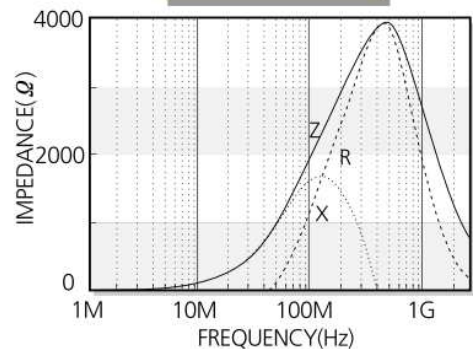
**CIV05U102NC**



**CIV05J102NC**



**CIV05J182NC**



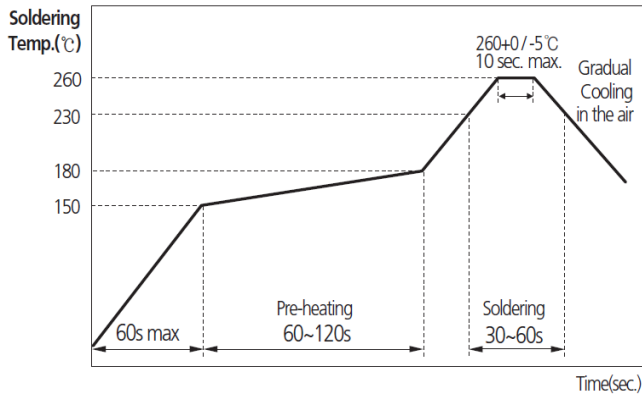
**PRODUCT IDENTIFICATION**

**CI V 05 U 102 N C**  
**(1) (2) (3) (4) (5) (6) (7)**

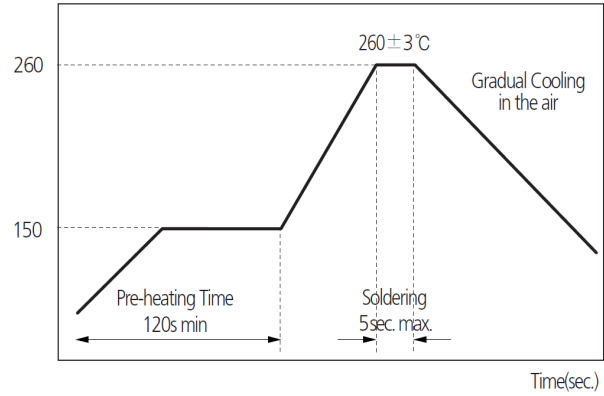
- (1) Chip Beads
- (2) Multi-layer type for GHz Noies suppression
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (601:600Ω, 102:1000Ω )
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4000

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.